

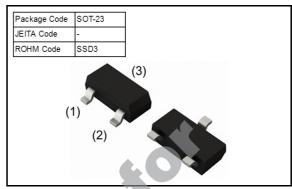
# BZX84B6V2LFH

Zener Diode

(AEC-Q101 qualified) Data sheet

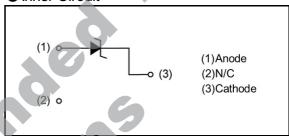
	•	
$P_{D}$	250	mW

### Outline



FeatureHigh reliabilitySmall mold type

Inner Circuit



ApplicationVoltage regulation

Packaging Specification

• r deridging openiodien						
Packing	Embossed Tape					
Reel Size(mm)	180					
Taping Width(mm)	8					
Basic Ordering Unit(pcs)	3000					
Taping Code	T116					
Marking	D3N					

StructureSilicon Epitaxial Planar

● Absolute Maximum Rating (T<sub>a</sub> = 25°C)

		T .	Limits	
Parameter	Symbol	Symbol Condition		Unit
Dougr dissinction	PD	an Class anavy substrate	250	mW
Power dissipation		on Glass-epoxy substrate	2.0	mW/°C
Junction temperature	T <sub>j</sub>	-	150	°C
Storage temperature	T <sub>stg</sub>	-	-65 <b>~</b> 150	°C

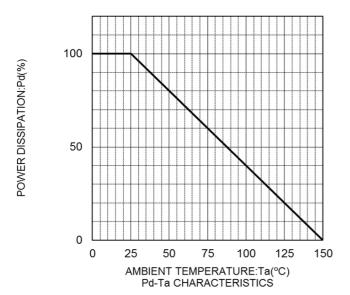
# ● Characteristic (T<sub>a</sub> = 25°C)

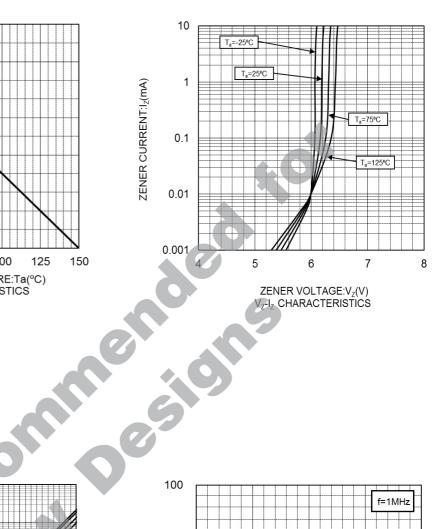
	Symbol										
P/N	P/N Zener		· Voltage:VZ(V)		Reverse Current: IR(µA)		Dynamic Impedance:ZZ(Ω)		Temperature Coefficient:y <sub>z</sub> (mV/°c)		
	MIN.	MAX.	l <sub>z</sub> (mA)	MAX.	V <sub>R</sub> (V)	MAX.	l <sub>z</sub> (mA)	MIN.	MAX.	l <sub>z</sub> (mA)	
BZX84B5V1LFH	5.00	5.20	5	2	2.0	60	5	-1.5	2.6	5	
BZX84B5V6LFH	5.49	5.71	5	1	2.0	40	5	-1.0	3.1	5	
BZX84B6V2LFH	6.08	6.32	5	3	4.0	10	5	0.9	3.8	5	
BZX84B6V8LFH	6.66	6.94	5	2	4.0	15	5	1.5	4.5	5	
BZX84B7V5LFH	7.35	7.65	5	1	5.0	15	5	2.2	5.0	5	
BZX84B8V2LFH	8.04	8.36	5	0.7	5.0	15	5	3.2	6.1	5	
BZX84B9V1LFH	8.92	9.28	5	0.5	6.0	15	5	3.9	6.9	5	
BZX84B10VLFH	9.80	10.20	5	0.2	7.0	20	5	5.0	8.0	5	
BZX84B11VLFH	10.80	11.20	5	0.1	8.0	20	5	5.8	8.8	5	
BZX84B12VLFH	11.80	12.20	5	0.1	8.0	25	5	6.8	9.8	5	
BZX84B13VLFH	12.70	13.30	5	0.1	8.0	30	5	7.9	11.0	5	
BZX84B15VLFH	14.70	15.30	5	0.1	10.0	30	5	9.4	12.6	5	
BZX84B16VLFH	15.70	16.30	5	0.1	11.0	40	5	11.0	14.3	5	
BZX84B18VLFH	17.60	18.40	5	0.1	13.0	45	5	12.6	15.8	5	
BZX84B20VLFH	19.60	20.40	5	0.1	14.0	55	5	14.3	17.3	5	
BZX84B22VLFH	21.60	22.40	5	0.1	15.0	55	5	15.8	19.3	5	
BZX84B24VLFH	23.50	24.50	5	0.1	17.0	70	5	17.3	22.6	5	
BZX84B27VLFH	26.50	27.50	2	0.1	19.0	80	2	19.3	25.8	2	
BZX84B30VLFH	29.40	30.60	2	0.1	21.0	80	2	22.6	28.5	2	
BZX84B33VLFH	32.30	33.70	2	0.1	23.0	80	2	25.8	31.1	2	
BZX84B36VLFH	35.30	36.70	2	0.1	25.0	90	. 2	28.5	34.0	2	

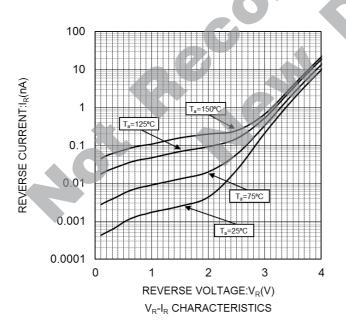
### Marking

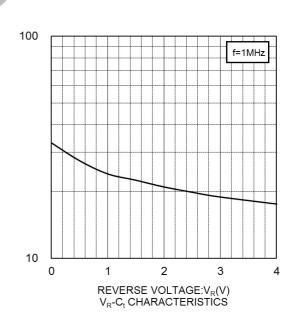
BZX84B33VLFH	32.30	33.70	2	0.1	23.0	80	2	25.8	31.1	2
BZX84B36VLFH	35.30	36.70	2	0.1	25.0	90	2	28.5	34.0	2
BZX84B36VLFH 35.30 36.70 2 0.1 25.0 90 2 28.5 34.0 2  V₂ test time is 40ms  ■ Marking										
P/N		Mari	king			P/N			Markir	ng
BZX84B5V1LF	BZX84B5V1LFH D3L BZX84B15VLFH D3X									
BZX84B5V6LF	74	D.	BM		BZX8	4B16VLF	H		D3Y	
BZX84B6V2LF	H	D:	BN		BZX8	4B18VLF	H		D3Z	
BZX84B6V8LF	H	DX:	3P		BZX8	4B20VLF	Ţ		D5A	
BZX84B7V5LF	BZX84B7V5LFH D3Q BZX84B22VLFH D5B									
BZX84B8V2LF	BZX84B8V2LFH D3R BZX84B24VLFH D5C									
BZX84B9V1LF	BZX84B9V1LFH D3S BZX84B27VLFH D5D									
BZX84B10VLF	BIOVLFH D3T BZX84B30VLFH D5E									
BZX84B11VLF	BZX84B11VLFH D3U BZX84B33VLFH D5F									
BZX84B12VLF	BZX84B12VLFH D3V BZX84B36VLFH D5G									
BZX84B13VLF	H	D3	SW .							

## Characteristic Curves



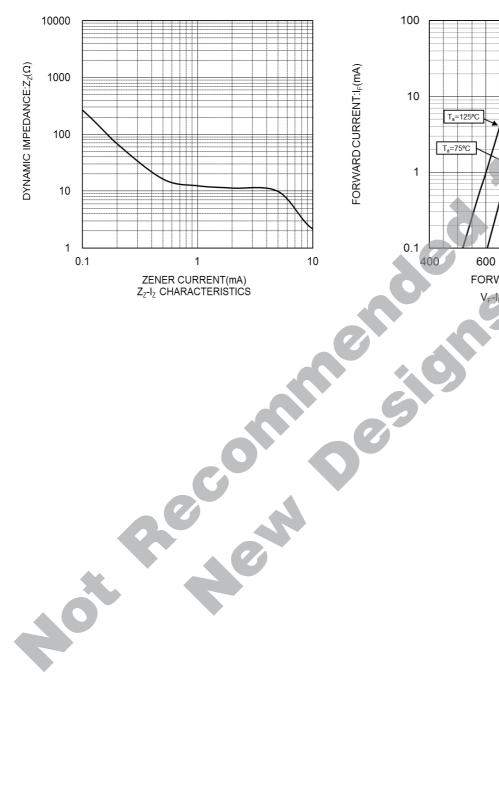


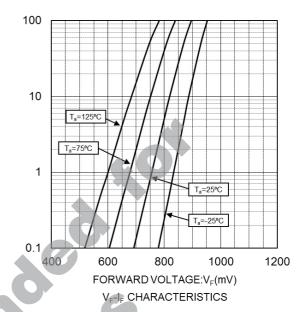




CAPACITANCE BETWEEN TERMINALS:C<sub>f</sub>(pF)

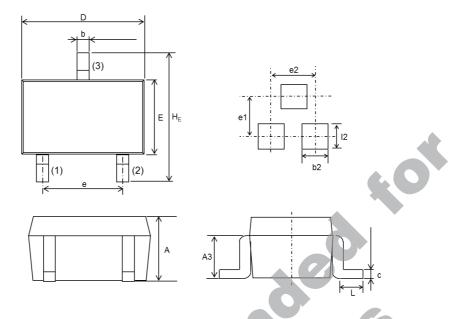
## Characteristic Curves





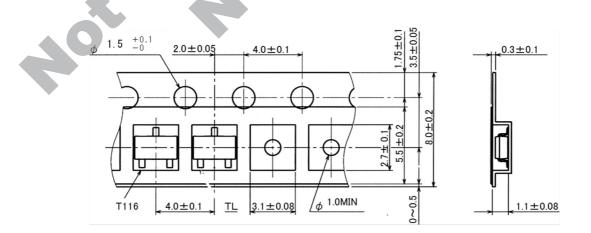
FORWARD CURRENT:I<sub>F</sub>(mA)

## ● Dimension (SSD3 SOT-23)



DIM		Milimeters			Inches	
DIIVI	Min.	Average	Max.	Min.	Average	Max.
А	0.85	0.95	1.15	0.033	0.037	0.045
A3	0.35	0.45	0.55	0.014	0.018	0.022
b	0.35	0.40	0.50	0.014	0.016	0.020
С	0.09	0.15	0.25	0.004	0.006	0.010
D	2.70	2.90	3.10	0.106	0.114	0.122
E	1.20	1.30	1.50	0.047	0.051	0.059
HE	2.20	2.40	2.60	0.087	0.094	0.102
L	0.20		-	0.008		-
е	1.70	1.90	2.10	0.067	0.075	0.083
12	1.00		-	0.039	)	-
b2	0.80	-	-	0.031		-
e1		2.10			0.083	-
e2		1.90	-	-	0.075	-

# ● Taping (Unit:mm)



# **Notice**

#### **Precaution on using ROHM Products**

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSII	CL ACCIII	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSIII	CLASSⅢ

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - [a] Installation of protection circuits or other protective devices to improve system safety
  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power, exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

#### **Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

#### **Precaution for Foreign Exchange and Foreign Trade act**

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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